

SRIDB6560R SERIES



PART NUMBERING SYSTEM

SRIDB	6 5 6 0	-	1 2 1 R	-	LF
TYPE	DIMENSIONS		IMPEDANCE		LEAD FREE

SHAPES AND DIMENSIONS

UNIT : mm



SPECIFICATION TABLE

PART NUMBER	RATED CURRENT (mA)	COMMON MODE IMPEDANCE ()		DCR () max.	WITHSTANDING VOLTAGE (Vdc)	INSULATION RESISTANCE () (min)	OPERATING TEMP. ()
		100MHz	300MHz				
SRIDB6560-121R-LF	500	120±25%	170 (TYP.)	0.12	100	100 M	-40~+85
SRIDB6560-301R-LF	500	300±25%	600 (TYP.)	0.12	100	100 M	-40~+85
SRIDB6560-501R-LF	500	500±25%	730 (TYP.)	0.12	100	100 M	-40~+85

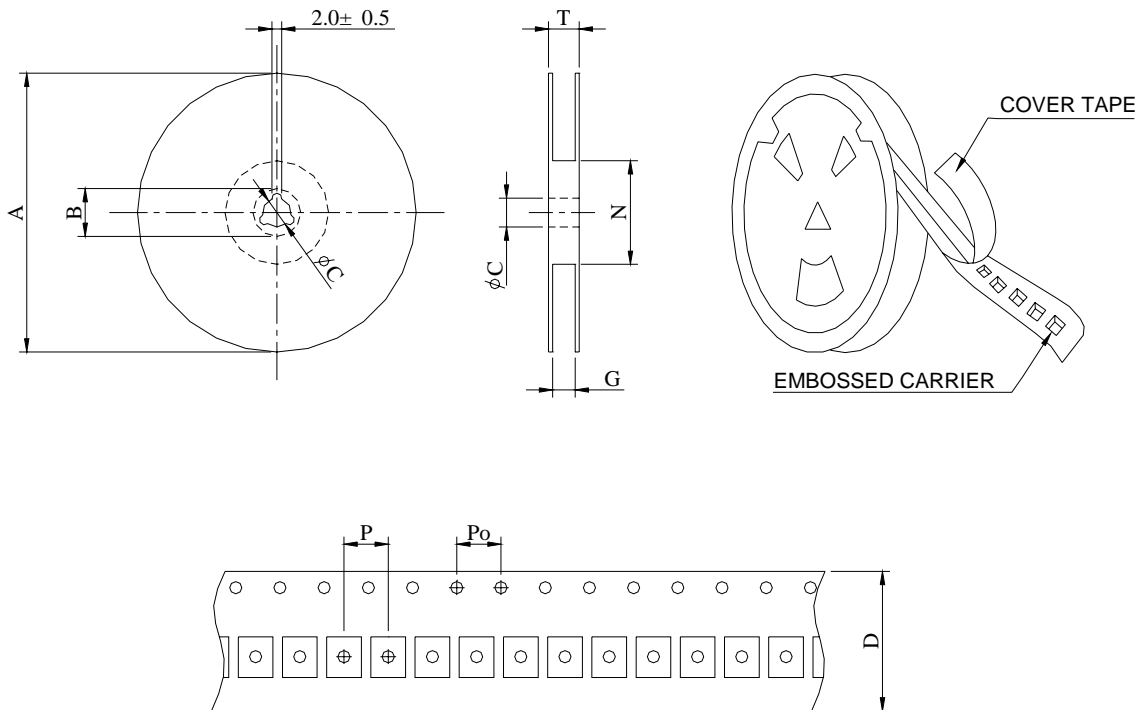
TEST EQUIPMENT : HP-4291A



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PACKAGING SPECIFICATION



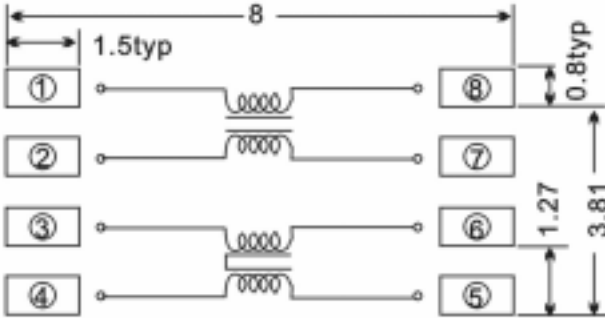
SERIES	STAYLE	Q ' TY (PCS)	DIMENSIONS (m/m)								
			A	B±0.8	C±0.5	D	G ⁺⁰	N ⁰	P	Po	T
SRIDB6560R	12	2000	330	21	13	12	12.4	75	8	4	16.4

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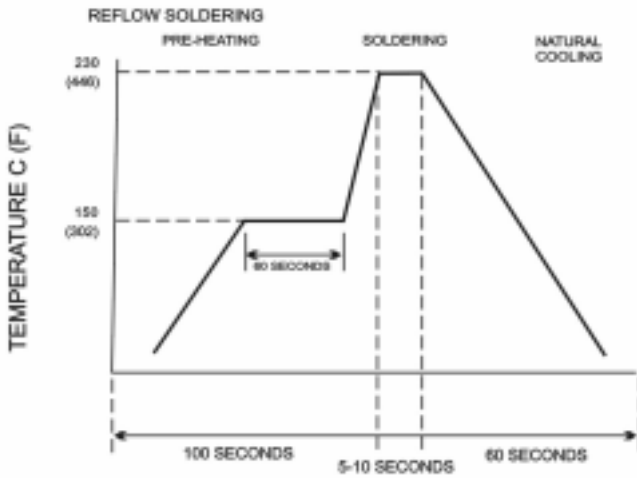


RECOMMENDED PC BOARD PATTERN (unit:mm)

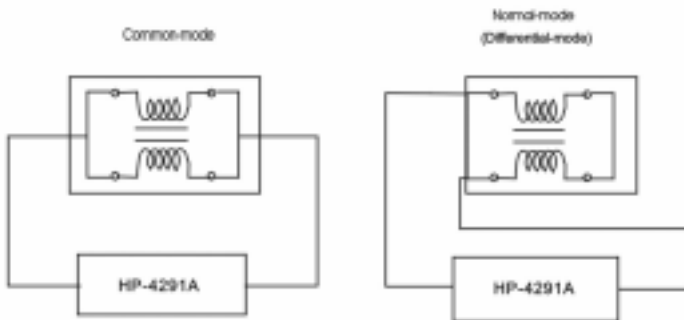
SRIDB 6560A/SRIDB 6560R



RECOMMENDED REFLOW SOLDERING CONDIDIONS



MEASURING CIRCUIT



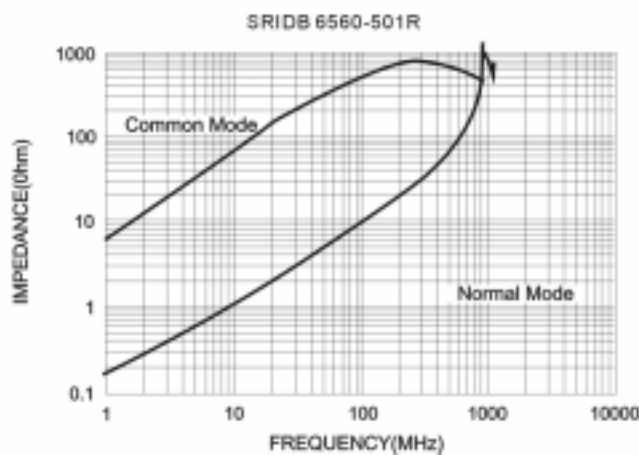
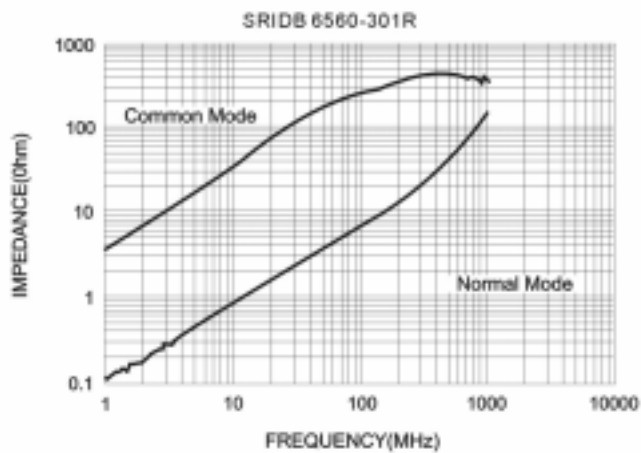
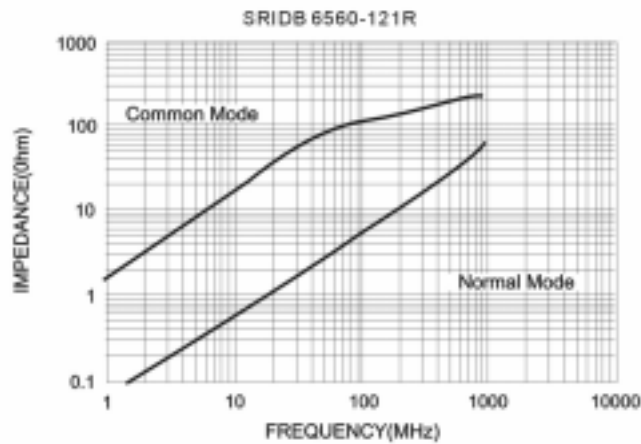


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TYPICAL ELECTRICAL CHARACTERISTICS

SRIDB 6560R SERIES COMMON MODE vs. NORMAL MODE CHARACTERISTICS




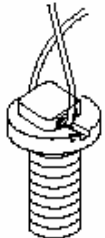
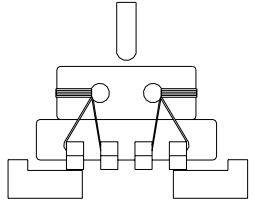


RELIABILITY TEST

TEST ITEMS	SPECIFICATIONS	TEST CONDITIONS/TEST METHODS
ELECTRICAL PERFORMANCE TEST		
INSERTION LOSS	REFER TO STANDARD ELECTRICAL CHARACTERISTIC LIST	HP-8714C OR EQUIV
IMPEDANCE		HP-4291A OR EQUIV
WITHSTAND VOLTAGE		CH-901 OR EQUIV
TEMPERATURE RISE TEST	40 MAX (t)	1. APPLIED THE ALLOWED DC CURRENT FOR 4 HOURS. 2. TEMPERATURE MEASURE BY DIGITAL SURFACE THERMOMETER.
<u>MECHANICAL PERFORMANCE TEST</u>		
SOLDER HEAT RESISTANCE	1. PRODUCT SHOULD HAVE NO EVIDENCE OF ELECTRICAL AND MICHANICAL DAMAGE. 2. IMPEDANCE SHOULD NOT CHANGE MORE THAN $\pm 10\%$.	PREHEAT : 150 60SECS SOLDER TEMPERATURE : 260 ± 5 FLUX : ROXIN DIP TIME : 5 ± 2 SECS <div style="text-align: right;"> </div>
VIBRATION TEST (LOW REQUENCY)		1. AMPLITUDE : 1.5mm 2. FREQUENCY : 10-55-10HZ / 1 MIN 3. DIRECTION : X, Y, Z 4. DURATION : 2 HRS/X, Y, Z
SHOCK TEST		INDUCTORS SHOULD BE DROPPED 10 TIMES FROM A HEIGHT OF 1m ONTO 3cm WOODEN BOARD.
SOLDERABILITY TEST	MORE THAN 90% OF TERMINDAL ELECTRODE SHOULD BE COVERED WITH SOLDER.	AFTER FLUXING, INDUCTOR SHALL BE DIPPED IN A MELTED SOLDER BATH AT 230 ± 5 FOR 5 SECONDS. <div style="text-align: right;"> </div>



RELIABILITY TEST

TEST ITEMS	SPECIFICATIONS	TEST CONDITIONS/TEST METHODS
MECHANICAL PERFORMANCE TEST		
COMPONENT ADHESION (PUSH TEST)	0.8Kg Min	THE DEVICE SHOULD BE REFLOW SOLDERED (232±5 FOR 10 SECONDS) TO A TINNED COPPER SUBSTRATE A DYNOMETER FORCE GAUGE SHOULD BE APPLIED TO THE SIDE OF THE COMPONENT THE DEVICE MUST WITH-ST1.0Kg WITHOUT AILURE OF THE TERMINATION ATTACHED TO COMPONENT 
COMPONENT ADHESION (PULL TEST)	0.75Kg Min	1.INSERT 10cm WIRE INTO THE REMAINING OPEN EYE BEND THE ENDS OF EVEN WIRE LENGTHS UPWARD AND WIND TOGETHER 2.TERMINAL SHALL NOT BE REMARKABLY DAMAGED 
FLEXTURE STRENGTH	THE FORCES APPLIED SHOULD NOT DAMAGE THE DIELECTRIC	SOLDER A CHIP ON A TEST SUBSTRATE, BEND THE SUBSTRATE BY 2mm AND RETURN. 
RESISTANCE TO SOLVENT TEST	THERE SHOULD BE NO CASE DEFORMATION, CHANGE IN APPEARANCE OR BITERATION OF MARKING	PRODUCT SHALL WITHSTAND 6 MINTES OF ALCOHOL



RELIABILITY TEST

TEST ITEMS	SPECIFICATIONS	TEST CONDITIONS/TEST METHODS
CLIMATIC TEST		
TEMPERATURE CHARACTERISTIC	1. APPEARANCE NO DAMAGE 2. IMPEDANCE : WITHIN±20% OF INITIAL VALUE	-25 +85
HUMIDITY TEST		1. TEMPERATURE : 60 ±2 2. HUMIDITY : 90-95%RH 3. APPLIED CURRENT : MAX RATED CURREN 4. TIME : 96±2 HOURS 5. MEASURE AT ROOM TEMPERATURE AFTER PLACING FOR 24HRS
LOW TEMPERATURE STORAGE		1. TEMPERATURE : -25 ±2 2. TIME : 96±2 HOURS 3. MEASURE AT ROOM TEMPERATURE AFTER PALCING FOR 24 Hrs
THERMAL SHOCK TEST		1. -40 FOR 5 MINUTES CONTINUE 1 HOUR AND 55 MINUTES +85 FOR 5 MINUTES CONTINUE 1 HOUR AND 55 MINUTE 2. TOTAL 4 CYCLES
HIGH TEMPERATURE STORAGE		1. APPLIED CURRENT : MAX RATED CURRENT 2. TEMPERATURE : 85 ±2 3. TIME : 96±2 HOURS 4. MEASURE AT ROOM TEMPERATURE AFTER PLACING FOR 24HRS
NOTE : PRODUCT ARE TO BE TESTED AFTER 4 HOUR AT ROOM TEMPERATURE		
<u>LIFE TEST</u>		
HIGH TEMPERATURE LOAD LIFE TEST	PRODUCT SHOULD BE NO EVIDENCE OF SHORT OR OPEN CIRCUIT	1. TEMPERATURE : 85±2 2. TIME : 500±12 HOURS 3. LOAD : ALLOWED DC CURRENT
HUMIDITY LOAD LIFE TEST		1. TEMPERATURE : 60±2 2. R.H. : 90-95% 3. TIME : 500±12 HOURS 4. LOAD : ALLOWED DC CURRENT